

Title (en)
METHOD FOR THE PRODUCTION OF A CIRCUIT BOARD INVOLVING THE REMOVAL OF A SUBREGION THEREOF, AND USE OF SUCH A METHOD

Title (de)
VERFAHREN ZUM HERSTELLEN EINER LEITERPLATTE UNTER ENTFERNUNG EINES TEILBEREICHS DERSELBEN SOWIE VERWENDUNG EINES DERARTIGEN VERFAHRENS

Title (fr)
PROCÉDÉ DE PRODUCTION D'UNE CARTE DE CIRCUIT PAR ÉLIMINATION D'UNE ZONE PARTIELLE DE LADITE CARTE, ET UTILISATION D'UN TEL PROCÉDÉ

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Application
EP 12816428 A 20121203

Priority
• AT 6572011 U 20111205
• AT 2012000303 W 20121203

Abstract (en)
[origin: WO2013082638A2] The invention relates to a method for producing a circuit board involving the removal of a subregion thereof. In said method, at least two layers or plies of the circuit board (1) are interconnected, the subregion (6) to be removed is prevented from being connected to an adjacent ply of the circuit board by providing a layer (7) of adhesion-preventing or bonding-preventing material, and peripheral zones (8) of the subregion (6) to be removed are separated from adjoining zones of the circuit board (1). According to the invention, a fissure formation and/or a detachment from the subregion (6) of the circuit board (1) to be removed is initiated in a subregion in or on the layer (7) of adhesion-preventing or bonding-preventing material, and the subregion (6) to be removed is then removed, thus making it possible to remove a subregion (6) to be removed from a circuit board (1) in a simple and reliable, and if necessary automated, manner. Also disclosed is a use of such a method for producing a multilayer circuit board (1) and especially for creating voids in such a circuit board (1).

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Citation (search report)
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